

PCMCIA Flash Memory Card

1 MEGABYTE through 40 MEGABYTE (Intel/Sharp based)

General Description

WEDC's FLA Series Flash memory cards offer high density linear Flash solid state storage solutions for code and data storage, high performance disk emulation and execute in place (XIP) applications in mobile PC and dedicated (embedded) equipment.

FLA series cards conform to PCMCIA international standard.

The card's control logic provides the system interface and controls the internal Flash memories. Card can be read/written in byte-wide or word-wide mode which allows for flexible integration into various systems. Combined with file management software, such as Flash Translation Layer (FTL), FLA Flash cards provide removable high-performance disk emulation.

The FLA series offers low power modes controlled by registers. Standard cards contain separate 2kB EEPROM memory for Card Information Structure (CIS) which can be used for easy identification of card characteristics.

The WEDC FLA series is based on Intel/Sharp Flash memories.

Note:

Standard options include attribute memory. Cards without attribute memory are available. Cards are also available with or without a hardware write protect switch.

Features

- Low cost High Density Linear Flash Card
- Supports 5V only systems or 5V systems with 12V VPP
- Based on Intel/Sharp FlashFile Components
- Fast Read Performance
 - 150ns or 200ns Maximum Access Time
- x8 / x16 Data Interface
- High Performance Random Writes
 8µs Typical Word Write Time
- Automated Write and Erase Algorithms
 - Command User Interface
- 100,000 Erase Cycles per Block
- 64K word symmetrical Block Architecture
- PC Card Standard Type I Form Factor

Architecture Overview

WEDC's FLA series is designed to support from 2 to 20, 4Mb, 8Mb or 16Mb components, providing a wide range of density options. Cards are based on the 28F008SA (8Mb) for 12V VPP applications or on the 28F004S5 (4Mb), 28F008S5 (8Mb) and 28F016S5 (16Mb) devices for 5V only applications. Devices codes for the 28F004S5, 28F008SA, 28F008S5 and the 28F016S5 are: A7H, A2H, A6H and AAh respectively. Systems should be able to recognize all four codes. Cards utilizing the 8Mb components provide densities ranging from 2MB to 20MB in 2MB increments, cards utilizing 16Mb components provide densities ranging from 4MB to 40MB in 4MB increments. 4 Mbit memory devices are used only for smallest capacity cards (1MB).

In support of the PC Card 95 standard for word wide access devices are paired. Therefore, the Flash array is structured in 64K word (128kBytes) blocks. Write, read and block erase operations can be performed as either a word or byte wide operation . By multiplexing A0, CE1# and CE2#, 8-bit hosts can access all data on data lines DQ0 - DQ7.

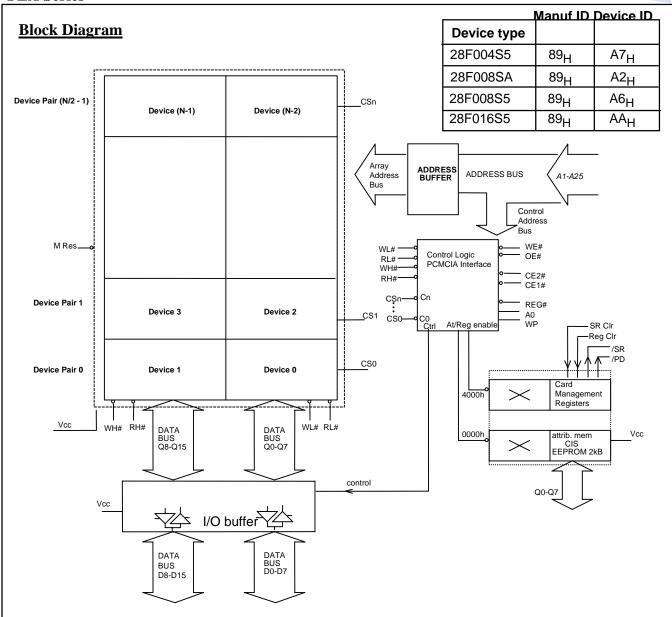
The FLA21-FLA36 series also supports the following PCMCIA compatible register functions: Soft Reset via the Configuration Option Register, Power Down (sleep mode) via the Configuration and Status Register and monitoring of Ready/Busy, Soft Reset and Power Down via the Card Status Register (cards without attribute memory and versions FLA51 - FLA66 do not have registers).

The FLA series cards conform with the PC Card Standard (PCMCIA) and JEIDA, providing electrical and physical compatibility. The PC Card form factor offers an industry standard pinout and mechanical outline, allowing density upgrades without system design changes.

WEDC's standard cards are shipped with WEDC's Logo. Cards are also available with blank housings (no Logo). The blank housings are available in both a recessed (for label) and flat housing. Please contact WEDC sales representative for further information on Custom artwork.

WHITE ELECTRONIC DESIGNS

FLA Series



Registers in Attribute Memory Space

ADDRESS	Register NAME							
4100h	Status Reg.							
4002h	Config. and Status Reg.							
4000h	Configuration Option Register							

COR

Configuration Option Register: ADRS=4000h Write Only

SRES									
D7	D6	D5	D4	Ď3	D2	D1	D0		

D7 Soft Reset, active High

1 = Reset State

0 = End Reset State

D6 LevelReq (not supported)

D5-D0 Configuration index (not supported)

CSR

Configuration Status Register: ADRS=4002h Write Only

not supported PDwn hot supported

D7 D6 D5 D4 D3 D2 D1 D0

D2 Power Down; active High

1=Place all memory devices in power down mode 0=normal operation Power On default=0

SR

Status	Re	ead Only						
not supp	oorted	SReset		PDwn	not supp	orted	R/BSY	
D7	D6	D5	D4	D3	D2	D1	D0	

D5 Represents the state of SRESET bit in COR (4000h) 1=Reset

0=Normal operation

Power On default D5=0

D3 Represents the state of Power Down bit (D2) in CSR (4002h) 1=Power Down

D0 Reflects the card's Ready/Busy signal (pin 16) driven by memory components Ready/Busy outputs. This bit allows software polling of the card's Ready/Busy status.

1=Ready

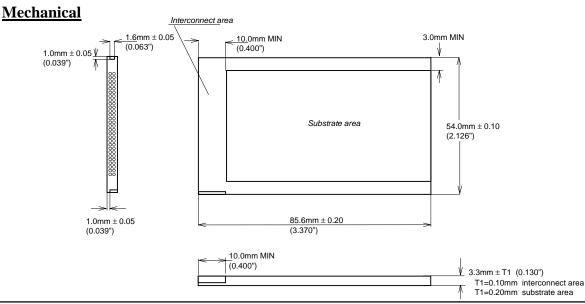


Pinout

Pin	Signal name	VO	Function	Active
1	GND		Ground	
2	DQ3	VO	Data bit 3	
3	DQ4	VO	Data bit 4	
4	DQ5	VO	Data bit 5	
5	DQ6	VO	Data bit 6	
6	DQ7	VO	Data bit 7	
7	CE1#	I	Card enable 1	LOW
8	A10	I	Address bit 10	
9	OE#	I	Output enable	LOW
10	A11	I	Address bit 11	
11	A9	ı	Address bit 9	
12	A8	ı	Address bit 8	
13	A13	I	Address bit 13	
14	A14	I	Address bit 14	
15	WE#	I	Write Enable	LOW
16	RDY/BSY#	0	Ready/Busy	LOW (4)
17	Vcc		Supply Voltage	
18	Vpp1		Prog. Voltage	N.C.
19	A16	I	Address bit 16	
20	A15	I	Address bit 15	
21	A12	I	Address bit 12	
22	A7	I	Address bit 7	
23	A6	I	Address bit 6	
24	A5	I	Address bit 5	
25	A4	I	Address bit 4	
26	A3	I	Address bit 3	
27	A2		Address bit 2	
28	A1	ı	Address bit 1	
29	A0	ı	Address bit 0	
30	DQ0	VO	Data bit 0	
31	DQ1	VO	Data bit 1	
32	DQ2	VO	Data bit 2	
33	WP	0	Write Potect	HIGH
34	GND		Ground	

Pin	Signal name	I/O	Function	Active
35	GND		Ground	
36	CD1#	0	Card Detect 1	LOW
37	DQ11	VO.	Data bit 11	
38	DQ12	VO	Data bit 12	
39	DQ13	VO	Data bit 13	
40	DQ14	V O	Data bit 14	
41	DQ15	ı	Data bit 15	
42	CE2#	ı	Card Enable 2	LOW
43	VS1	0	Voltage Sense 1	N.C.
44	RFU		Reserved	
45	RFU		Reserved	
46	A17	-	Address bit 17	
47	A18	I	Address bit 18	
48	A19	I	Address bit 19	
49	A20	I	Address bit 20	2MB(3)
50	A21	- 1	Address bit 21	4MB(3)
51	Vcc		Supply Voltage	
52	Vpp2		Prog. Voltage	N.C.
53	A22	I	Address bit 22	8MB(3)
54	A23	I	Address bit 23	16MB(3)
55	A24	I	Address bit 24	32MB(3)
56	A25	I	Address bit 25	64MB(3)
57	VS2	0	Voltage Sense 2	N.C.
58	RST	I	Card Reset	HIGH (4)
59	Wait#	0	Extended Bus cycle	Low(2,4)
60	RFU		Reserved	
61	REG#	I	Attrib Mem Select	
62	BVD2	0	Bat. Volt. Detect 2	(2)
63	BVD1	0	Bat. Volt. Detect 1	(2)
64	DQ8	VO	Data bit 8	
65	DQ9	VO	Data bit 9	
66	DQ10	0	Data bit 10	
67	CD2#	0	Card Detect 2	LOW
68	GND		Ground	

- 1. RDY/BSY signal is an "Open drain" type output, pull-up resistor on host side is required.
- 2. Wait#, BVD1 and BVD2 are driven high for compatibility.
- 3. Shows density for which specified address bit is MSB. Higher order address bits are no connects (ie 4MB A21 is MSB A22 A25 are NC).
- 4. NC No Connection for FLA51 FLA66.





Card Signal Description

Symbol	Туре	Name and Function
A0 - A25	INPUT	ADDRESS INPUTS: A0 through A25 enable direct addressing of up to
		64MB of memory on the card. Signal A0 is not used in word access
		mode. A25 is the most significant bit
DQ0 - DQ15	INPUT/OUTPUT	DATA INPUT/OUTPUT: DQ0 THROUGH DQ15 constitute the bi-
		directional databus. DQ15 is the MSB.
CE1#, CE2#	INPUT	CARD ENABLE 1 AND 2: CE1# enables even byte accesses, CE2#
,		enables odd byte accesses. Multiplexing A0, CE1# and CE2# allows 8-
		bit hosts to access all data on DQ0 - DQ7.
OE#	INPUT	OUTPUT ENABLE: Active low signal gating read data from the
		memory card.
WE#	INPUT	WRITE ENABLE: Active low signal gating write data to the memory
		card.
RDY/BSY#	OUTPUT	READY/BUSY OUTPUT: Indicates status of internally timed erase or
		program algorithms. A high output indicates that the card is ready to
		accept accesses. A low output indicates that one or more devices in the
		memory card are busy with internally timed erase or write activities.
CD1#, CD2#	OUTPUT	CARD DETECT 1 and 2: Provide card insertion detection. These
•		signals are internally connected to ground on the card. The host shall
		monitor these signals to detect card insertion (pulled-up on host side).
WP	OUTPUT	WRITE PROTECT: Write protect reflects the status of the Write Protect
		switch on the memory card. WP set to high = write protected, providing
		internal hardware write lockout to the Flash array.
		If card does not include optional write protect switch, this signal will be
		pulled low internally indicating write protect = "off".
VPP1, VPP2	N.C.	PROGRAM/ERASE POWER SUPPLY: Provides programming
		voltages for card (12V). Not connected for 5V only card.
VCC		CARD POWER SUPPLY: (5.0V).
GND		CARD GROUND
REG#	INPUT	ATTRIBUTE MEMORY SELECT : Active low signal, enables access to
		Attribute Memory Plane, occupied by Card Information Structure and
		Card Registers.
RST	INPUT	RESET: Active high signal for placing card in Power-on default state.
		Reset can be used as a Power-Down signal for the memory array.
WAIT#	OUTPUT	WAIT: This signal is pulled high internally for compatibility. No wait
		states are generated.
BVD1, BVD2	OUTPUT	BATTERY VOLTAGE DETECT: These signals are pulled high to
,		maintain SRAM card compatibility.
VS1, VS2	OUTPUT	VOLTAGE SENSE: Notifies the host socket of the card's VCC
•		requirements. VS1 and VS2 are open to indicate a 5V card .
RFU		RESERVED FOR FUTURE USE
N.C.		NO INTERNAL CONNECTION TO CARD: pin may be driven or left
		floating

Functional Truth Table

READ function Common Memory Attribute Memory

Function Mode	/CE2	/CE1	A0	/OE	/WE	/REG	D15-D8	D7-D0	/REG	D15-D8	D7-D0
Standby Mode	Н	Н	Χ	Χ	Х	Χ	High-Z	High-Z	Х	High-Z	High-Z
Byte Access (8 bits)	Н	L	L	L	Н	Н	High-Z	Even-Byte	L	High-Z	Even-Byte
	Н	L	Н	L	Н	Н	High-Z	Odd-Byte	L	High-Z	Not Valid
Word Access (16 bits)	L	L	Х	L	Н	Н	Odd-Byte	Even-Byte	L	Not Valid	Even-Byte
Odd-Byte Only Access	L	Н	Х	L	Н	Н	Odd-Byte	High-Z	L	Not Valid	High-Z
WRITE function											
Standby Mode	Н	Н	Χ	Χ	Х	Χ	X	X	Х	Х	Х
Byte Access (8 bits)	Н	L	L	Н	L	Н	Х	Even-Byte	L	Х	Even-Byte
	Н	L	Н	Н	L	Н	Х	Odd-Byte	L	Х	Х
Word Access (16 bits)	L	L	Х	Н	L	Н	Odd-Byte	Even-Byte	L	Х	Even-Byte
Odd-Byte Only Access	L	Н	Χ	Н	L	Н	Odd-Byte	Х	L	Х	Х



Absolute Maximum Ratings (1)

Operating Temperature TA (ambient)	
Commercial	0°C to +60 °C
Industrial	-40°C to +85 °C
Storage Temperature	
Commercial	-30°C to +80 °C
Industrial	-40°C to +85 °C
Voltage on any pin relative to VSS	-0.5V to VCC+0.5V
VCC supply Voltage relative to VSS	-0.5V to +7.0V

Note:

(1) Stress greater than those listed under "Absolute Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at these or any other conditions greater than those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Characteristics (1)

Symbol	Parameter	Density	Notes	Typ ⁽³⁾	Max	Units	Test Conditions
		(Mbytes)					
ICCR	VCC Read Current	All			35	mA	VCC = VCCmax
							tcycle = 150ns, CMOS levels
ICCW	VCC Program Current	All	28F008S5 28F016S5		75	mA	
Iccw	VCC Program Current	All	28F008SA		30	mA	
IPPW	VPP Program Current	All	Vpp=12V		30	mA	
ICCE	VCC Erase Current	All			100	mA	
Iccs	VCC Standby Current	2MB	2	110	230	μΑ	VCC = VCCmax
(CMOS)		20MB	28F008SA	900			Control Signals = VCC
(CIVICO)		2MB	2	60			Reset = VSS, CMOS levels
		20MB	28F008S5	420			
		4MB	2	60			
		40MB	28F016S5	380			

CMOS Test Conditions: VCC = 5V \pm 5%, VIL = VSS \pm 0.2V, VIH = VCC \pm 0.2V

Notes

- 1. All currents are RMS values unless otherwise specified. ICCR, ICCW and ICCE are based on Byte wide operations. For 16 bit operation values are double.
- 2. Control Signals: CE₁#, CE₂#, OE#, WE#, REG#.
- 3. Typical: VCC = 5V, T = +25C.

Symbol	Parameter	Notes	Min	Max	Units	Test Conditions
ILI	Input Leakage Current	1		±20	μΑ	VCC = VCCMAX Vin =VCC or VSS
I _{LO}	Output Leakage Current	1		±20	μA	VCC = VCCMAX Vout = VCC or VSS
V _{IL}	Input Low Voltage	1	0	0.8	V	
V _{IH}	Input High Voltage	1	0.7VCC	VCC+0.5	V	
V _{OL}	Output Low Voltage	1		0.4	V	IOL = 3.2mA
VoH	Output High Voltage	1	VCC-0.4	VCC	V	IOH = -2.0mA
V _{LKO}	VCC Erase/Program Lock Voltage	1	2.0		V	

- 1. Values are the same for byte and word wide modes for all card densities.
- 2. Exceptions: Leakage currents on CE1#, CE2#, OE#, REG# and WE# will be < 500 μA when VIN = GND due to internal pull-up resistors. Leakage currents on RST will be <150μA when VIN=VCC due to internal pull-down resistor.



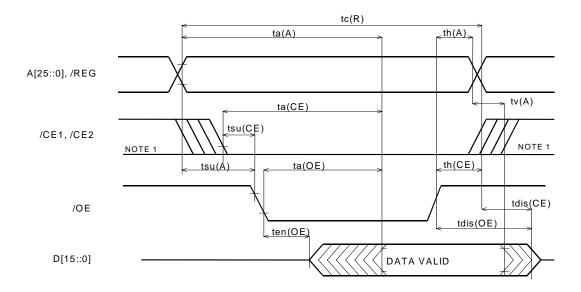
AC Characteristics

Read Timing Parameters

		150ns	.	
SYMBOL (PCMCIA)	Parameter	Min	Max	Unit
t _C (R)	Read Cycle Time	150		ns
t _a (A)	Address Access Time		150	ns
t _a (CE)	Card Enable Access Time		150	ns
t _a (OE)	Output Enable Access Time		75	ns
t _{su} (A)	Address Setup Time		20	ns
t _{su} (CE)	Card Enable Setup Time		0	ns
t _h (A)	Address Hold Time		20	ns
t _h (CE)	Card Enable Hold Time		20	ns
t _v (A)	Output Hold from Address Change		0	ns
t _{dis} (CE)	Output Disable Time from CE#		75	ns
t _{dis} (OE)	Output Disable Time from OE#		75	ns
t _{en} (CE)	Output Enable Time from CE#	5		ns
t _{en} (OE)	Output Enable Time from OE#	5		ns
t _{rec} (RSR)	Power Down recovery to Output Delay. VCC = 5V		500	ns

Note: AC timing diagrams and characteristics are guaranteed to meet or exceed PCMCIA 2.1 specifications.

Read Timing Diagram



Note: Signal may be high or low in this area.

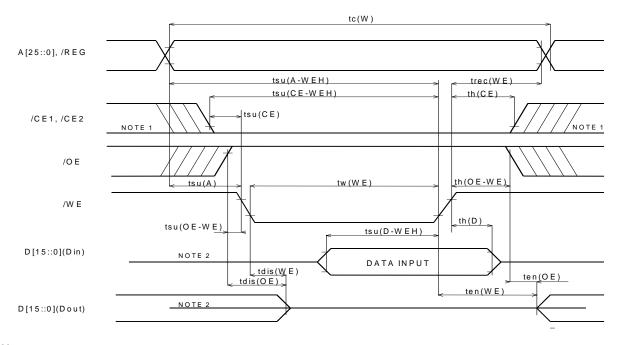


Write Timing Parameters

		150ns		
SYMBOL (PCMCIA)	Parameter	Min	Max	Unit
t _C W	Write Cycle Time	150		ns
t _w (WE)	Write Pulse Width	80		ns
t _{su} (A)	Address Setup Time	20		ns
t _{su} (A-WEH)	Address Setup Time for WE#	100		ns
t _{su} (CE- WEH)	Card Enable Setup Time for WE#	100		ns
t _{su} (D-WEH)	Data Setup Time for WE#	50		ns
t _h (D)	Data Hold Time	20		ns
t _{rec} (WE)	Write Recover Time	20		ns
t _{dis} (WE)	Output Disable Time from WE#		75	ns
t _{dis} (OE)	Output Disable Time from OE#		75	ns
t _{en} (WE)	Output Enable Time from WE#	5		ns
t _{en} (OE)	Output Enable Time from OE#	5		ns
t _{su} (OE-WE)	Output Enable Setup from WE#	10		ns
t _h (OE-WE)	Output Enable Hold from WE#	10		ns
t _{su} (CE)	Card Enable Setup Time from OE#	0		ns
t _h (CE)	Card Enable Hold Time	20		ns

Note: AC timing diagrams and characteristics are guaranteed to meet or exceed PCMCIA 2.1 specifications.

Write Timing Diagram



- 1. Signal may be high or low in this area
- 2. When the data I/O pins are in the output state, no signals shall be applied to the data pins (D15 D0) by the host system.



Data Write and Erase Performance (1,3)

 $VCC = 5V \pm 5\%, T_A = 0C \text{ to } + 70C$

Symbol	Parameter	Notes	Min	Typ ⁽¹⁾	Max	Units
t _{WHQV1}	Word/Byte Program time	4		8		μs
t _{EHQV1}						
t _{WHQV2}	Block Program Time	device SA		0.6	2.1	sec
t _{EHQV2}		device S5	0.4	0.5		
	Block Erase Time	device SA		1.6	10	sec
		device S5	0.9	1.1		

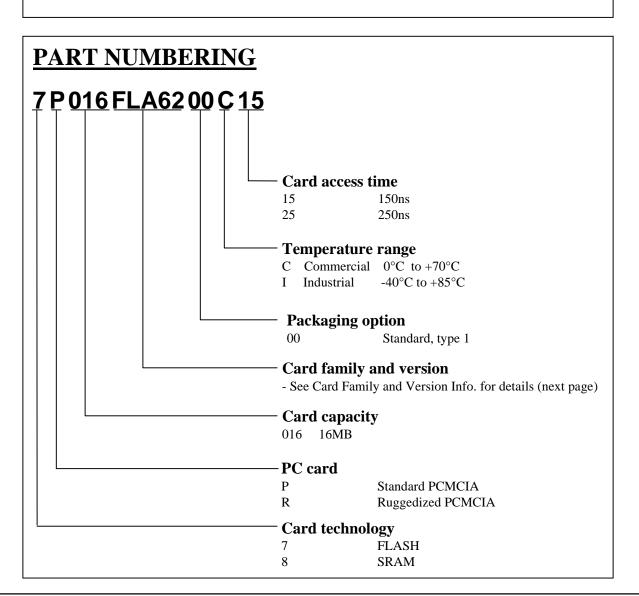
- 1. Typical: Nominal voltages and $T_A = 25C$.
- 2. Excludes system overhead.
- 3. Valid for all speed options.
- 4. To maximize system performance RDY/BSY# signal should be polled.



PRODUCT MARKING WED 7P016FLA6200C15 C995 9915 EDI Date code Lot code / trace number Part number Company Name

Some products are currently marked with our pre-merger company name/acronym (EDI). During our transition period, some products will also be marked with our new company name/acronym (WED).

Starting October 2000 all PCMCIA products will be marked only with the WED prefix.





Card Family and Version Information

FLA21-FLA24	Based on 28F008SA (requires 12V VPP for programming and erase functions))
T LA41-T LA4	Dased on Zor vvosa (Tedunes 12 v Vrr 101 blogramming and crase functions)	,

FLA21	No Attribute Memory, no Write Protect
FLA22	With Attribute Memory, no Write Protect
FLA23	No Attribute Memory, with Write Protect
FLA24	With Attribute Memory, with Write Protect

Example P/N **7P004FLA2200C15**

FLA25-FLA28 Based on 28F008S5 for 5V only applications

FLA25	No Attribute Memory, no Write Protect
FLA26	With Attribute Memory, no Write Protect
FLA27	No Attribute Memory, with Write Protect
FLA28	With Attribute Memory, with Write Protect

Example P/N **7P004FLA2600C15**

<u>FLA29-FLA32</u> Based on **28F016S5** for 5V only applications

FLA29	No Attribute Memory, no Write Protect
FLA30	With Attribute Memory, no Write Protect
FLA31	No Attribute Memory, with Write Protect
FLA32	With Attribute Memory, with Write Protect

Example P/N **7P004FLA3000C15**

<u>FLA33-FLA36</u> Based on **28F004S5** for 5V only applications

FLA33	No Attribute Memory, no Write Protect
FLA34	With Attribute Memory, no Write Protect
FLA35	No Attribute Memory, with Write Protect
FLA36	With Attribute Memory, with Write Protect

Example P/N **7P004FLA3600C15**

FLA51-FLA54 Based on **28F008SA** Similar to FLA21-FLA24: does not support registers and signals

RST, RDY/BSY, Wait are not connected

FLA51	No Attribute Memory, no Write Protect
FLA52	With Attribute Memory, no Write Protect
FLA53	No Attribute Memory, with Write Protect
FLA54	With Attribute Memory, with Write Protect

Example P/N **7P004FLA5200C15**

FLA55-FLA58 Based on **28F008S5** Similar to FLA25-FLA28: does not support registers and signals

RST, RDY/BSY, Wait are not connected

FLA55	No Attribute Memory, no Write Protect
FLA56	With Attribute Memory, no Write Protect
FLA57	No Attribute Memory, with Write Protect
FLA58	With Attribute Memory, with Write Protect

Example P/N **7P004FLA5600C15**

PCMCIA Flash Memory Card

FLA Series



FLA59-FLA62 Based on 28F016S5 Similar to FLA29-FLA32: does not support registers and signals

RST, RDY/BSY, Wait are not connected

FLA59 No Attribute Memory, no Write Protect
 FLA60 With Attribute Memory, no Write Protect
 FLA61 No Attribute Memory, with Write Protect
 FLA62 With Attribute Memory, with Write Protect

Example P/N 7P004FLA6000C15

FLA63-FLA66 Based on **28F004S5** Similar to FLA33-FLA36: does not support registers and signals

RST, RDY/BSY, Wait are not connected

FLA63 No Attribute Memory, no Write Protect
 FLA64 With Attribute Memory, no Write Protect
 FLA65 No Attribute Memory, with Write Protect
 FLA66 With Attribute Memory, with Write Protect

Example P/N **7P004FLA6600C15**



Ordering Information

7P XXX FLAYY SS T ZZ

where

XXX:	002 1)	2MB
	004	4MB
	006 1)	6MB
	008	8MB
	010 1)	10MB
	012	12MB
	014 ¹⁾	14MB
	016	16MB
	018 ¹⁾	18MB
	020	20MB
	024 ²⁾	24MB
	028 ²⁾	28MB
	032 ²⁾	32MB
	036 ²⁾	36MB
	040 ²⁾	40MB

 $^{^{\}rm 1)}$ available only for FLA21-FLA24, FLA25-FLA28, FLA51-FLA54, and FLA55-FLA59

FLAYY: Card Family and Version (See Card Family and Version Information)

SS:	00	WEDC Logo Silkscreen
	01	Blank Housing, Type I
	02	Blank Housing, Type I Recessed

T:	\mathbf{C}	Commercial	0° C to $+70^{\circ}$ C
	I**	Industrial	-40°C to +85°C

ZZ: 15 150ns

Notes: Options without attribute memory and with hardware write protect switch are available.

²⁾ available only for FLA29-FLA32 and FLA59-FLA62

^{**} Denotes advanced information.



CIS Information for FLA Series Cards

Address	Value	Description	Address	Value	Description
00H	01H	CISTPL_DEVICE	30H	F6H	EDI TPLMID_MANF: LSB
02H	03H	TPL_LINK	32H	01H	EDI TPLMID_MANF: MSB
04H	53H	FLASH = 150ns (device writable)	34H	00H	LSB: Number Not Assigned
06H	06H	CARD SIZE: 2MB	36H	00H	MSB: Number Not Assigned
	0EH	4MB	38H	15H	CISTPL_VERS1
	16H	6MB	3AH	47H	TPL_LINK
	1EH	8MB	3CH	05H	TPLLV1_MAJOR
	26H	10MB	3EH	00H	TPLLV1_MINOR
	2EH	12MB	40H	45H	Е
	36H	14MB	42H	44H	D
	3EH	16MB	44H	49H	I
	46H	18MB	46H	37H	7
	4EH	20MB	48H	50H	Р
	5EH	24MB	4AH	30H	0
	6EH	28MB	4CH		х
	7EH	32MB	4EH		х
	8EH	36MB	50H	46H	F
	9EH	40MB	52H	4CH	L
08H	FFH	END OF DEVICE	54H	41H	А
0AH	18H	CISTPL_JEDEC_C	56H	32H	2 based on
0CH	02H	TPL_LINK	58H	32H	2 28F008SA
0EH	89H	INTEL - ID		32H	2 based on
10H	A2H	INTEL 28F008SA - ID		36H	6 28F008S5
	A6H	INTEL 28F008S5 - ID		33H	3 based on
	AAH	INTEL 28F016S5 - ID		30H	0 28F016S5
12H	17H	CISTPL_DEVICE_A	5AH	2DH	-
14H	03H	TPL_LINK	5CH	2DH	-
16H	42H	EEPROM - 200ns	5EH	2DH	-
18H	01H	Device Size = 2KBytes	60H	31H	1
1AH	FFH	END OF TUPLE	62H	35H	5
1CH	1EH	CISTPL_DEVICEGEO	64H	20H	SPACE
1EH	06H	TPL_LINK	66H	00H	END TEXT
20H	02H	DGTPL_BUS	68H	43H	С
22H	11H	DGTPL_EBS	6AH	4FH	0
24H	01H	DGTPL_RBS	6CH	50H	Р
26H	01H	DGTPL_WBS	6EH	59H	Y
28H	01H	DGTPL_PART	70H	52H	R
2AH	01H	FLASH DEVICE	72H	49H	I
		NON-INTERLEAVED	74H	47H	G
2CH	20H	CISTPL_MANFID	76H	48H	Н
2EH	04H	TPL_LINK(04H)	78H	54H	Т
			7AH	20H	SPACE



CIS Information for FLA Series Cards (Cont.)

Address	Value	Description
7CH	45H	E
7EH	4CH	L
80H	45H	Е
82H	43H	С
84H	54H	T
86H	52H	R
88H	4FH	0
8AH	4EH	N
8CH	49H	ı
8EH	43H	С
90H	20H	SPACE
92H	44H	D
94H	45H	Е
96H	53H	S
98H	49H	I
9AH	47H	G
9CH	4EH	N
9EH	53H	S
A0H	20H	SPACE
A2H	49H	I
A4H	4EH	N
A6H	43H	С
A8H	4FH	0
AAH	52H	R
ACH	50H	Р
AEH	4FH	0
B0H	52H	R
B2H	41H	A
B4H	54H	Т
B6H	45H	Е
B8H	44H	D
BAH	20H	SPACE
BCH	00H	END TEXT
BEH	31H	1
C0H	39H	9
C2H	39H	9
C4H	37H	7
C6H	00H	END TEXT
C8H	FFH	END OF LIST
CAH	1AH	CISTPL_CONF
CCH	05H	TPL_LINK
CEH	01H	TPCC_SZ
D0H	00H	TPCC_LAST
D2H	00H	TPCC_RADR
D4H	40H	TPCC_RADR
D6H	03H	TPCC_RMSK
D8H	00H	NULL CONTROL TUPLE
DAH	FFH	CISTPL_END
DCH	00H	INVALID ADDRESS



Revision History:

rev level description date

rev 0 initial release May 26, 1998

rev 1 Logo change May 27, 1999

rev 2 Change in Ordering info: January 31, 2000

added FLA24, took "EDI" off of all part numbers, changed "EDI Silkscreen" to "WEDC Logo Silkscreen"

rev 3 Heading/Logo changed and May 30, 2000

added to all pages

Changes to Pages 1 & 12

Pages 9-11:

Added Product Marking Info,

added Family and Version Information,

edited Ordering Info,

edited General description

and edited Architecture Overview

rev 4 Corrected Errors on pgs. 6 & 7 August 1, 2000

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